

RoHS Compliant

| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A1 | Release To ECN20110505 | 2011.05.13 | Seven |
| A2 | Release To ECN20130304 | 2013.03.20 | Seven |
| A3 | Release To ECN20150613 | 2015.06.30 | Michelle |

Specification
 1.Current Rating:2A
 2.Voltage Rating:100V AC/DC
 3.Contact Resistance:20mΩ Max.
 4.Insulation Resistance:1000MΩ Min.
 5.Dielectric Withstanding Voltage:AC800V/Minute
 6.Operating Temperature:-25℃~85℃

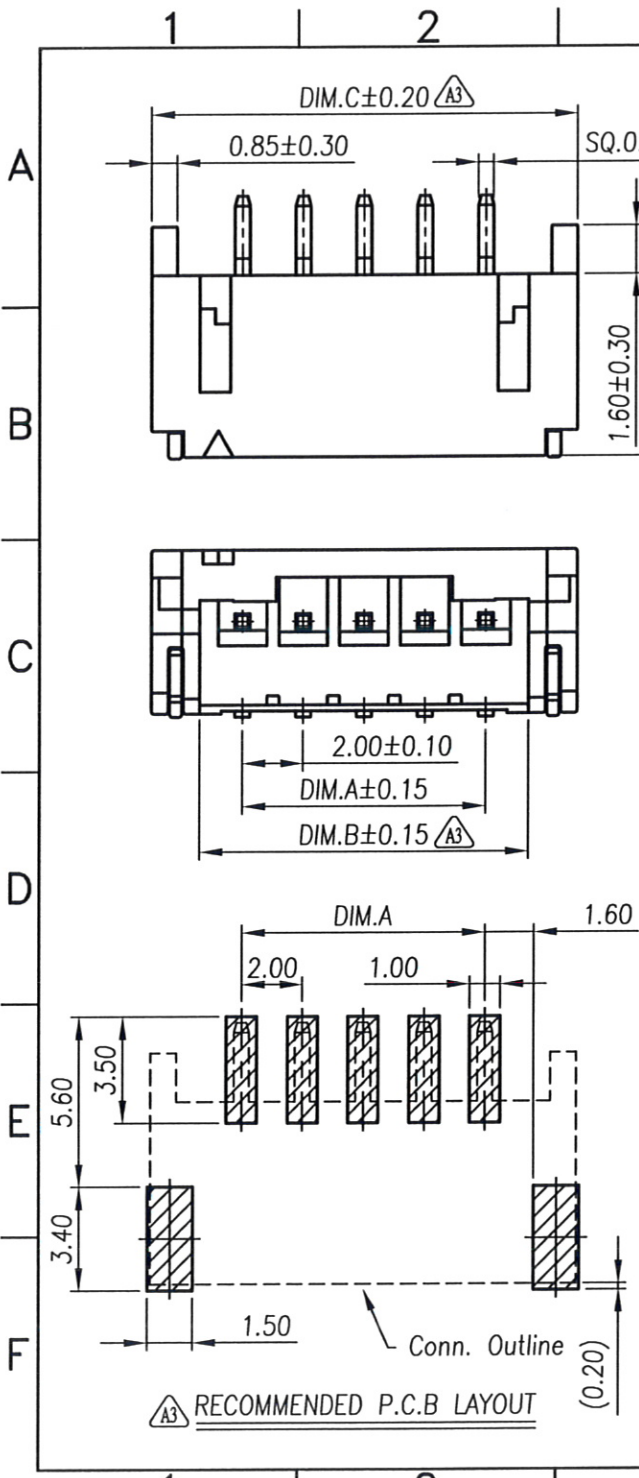
Material:
 1.Housing:High Temperature Thermoplastic UL94V-0
 2.Tab:Copper Alloy
 3.Contact Pin:Copper Alloy SQ. Pin 0.50mm

Finish:
 1.Housing:See P/N Option
 2.Tab:Bright Tin Over Nickel
 3.Contact Pin:See P/N Option


Part No.: AS05701 XX X X X 2
 No. Of Pin 02~16
 Packing 1:T&R 4:Tube

Housing Material
 5:HTN UL94V-0 Natural None H.F
 K:HTN UL94V-0 Natural H.F

Plating
 1:Bright Tin Plated Over Nickel
 2:Matte Tin Plated Over Nickel
 3:Gold Flash Over Nickel



| PIN | DIM.A | DIM.B | DIM.C | PIN | DIM.A | DIM.B | DIM.C |
|-----|-------|-------|-------|-----|-------|-------|-------|
| 02 | 2.00 | 4.80 | 8.00 | 10 | 18.00 | 20.80 | 24.00 |
| 03 | 4.00 | 6.80 | 10.00 | 11 | 20.00 | 22.80 | 26.00 |
| 04 | 6.00 | 8.80 | 12.00 | 12 | 22.00 | 24.80 | 28.00 |
| 05 | 8.00 | 10.80 | 14.00 | 13 | 24.00 | 26.80 | 30.00 |
| 06 | 10.00 | 12.80 | 16.00 | 14 | 26.00 | 28.80 | 32.00 |
| 07 | 12.00 | 14.80 | 18.00 | 15 | 28.00 | 30.80 | 34.00 |
| 08 | 14.00 | 16.80 | 20.00 | 16 | 30.00 | 32.80 | 36.00 |
| 09 | 16.00 | 18.80 | 22.00 | | | | |



金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

| | | | | |
|--------------------------------------|------------|------------------------|--|-----------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | PROJ. | TITLE: Wire To Board Wafer 2.00mm 90° SMT Single Row | |
| .x± 0.35 | x.* 2' | APR. C.F.Liao 20150630 | PART NO. AS05701XXXXX2 | DWG NO. AS05701XXXXX2 |
| .xx± 0.25 | .x.* 1' | CHK. Abel 20150630 | UNITS: mm CUSTOMER DRAWING | |
| .xxx± 0.15 | .xx.* 0.5' | DRA. Michelle 20150630 | SIZE: A4 | SCALE 4:1 |
| | | | SHEET 1 / 2 | REV A3 V |

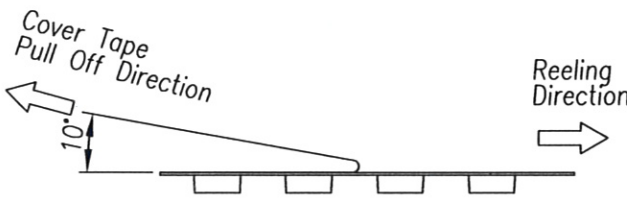
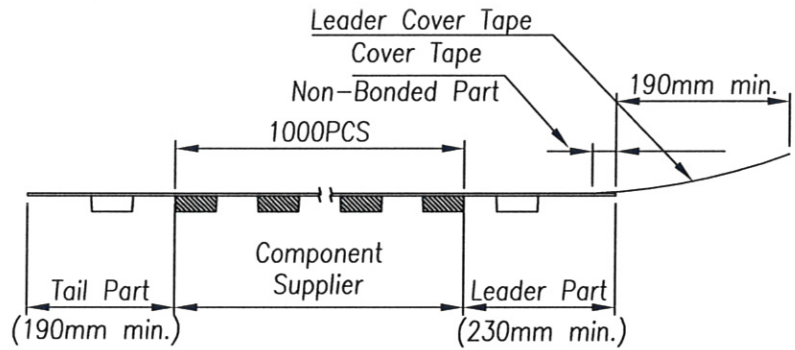
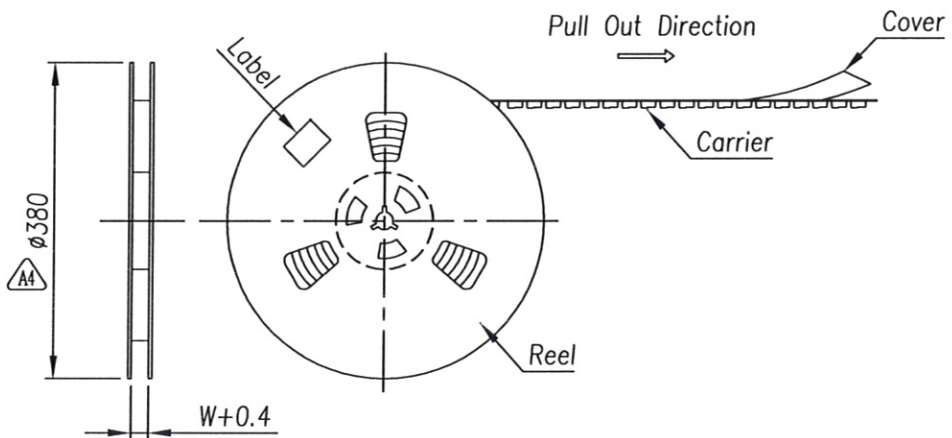
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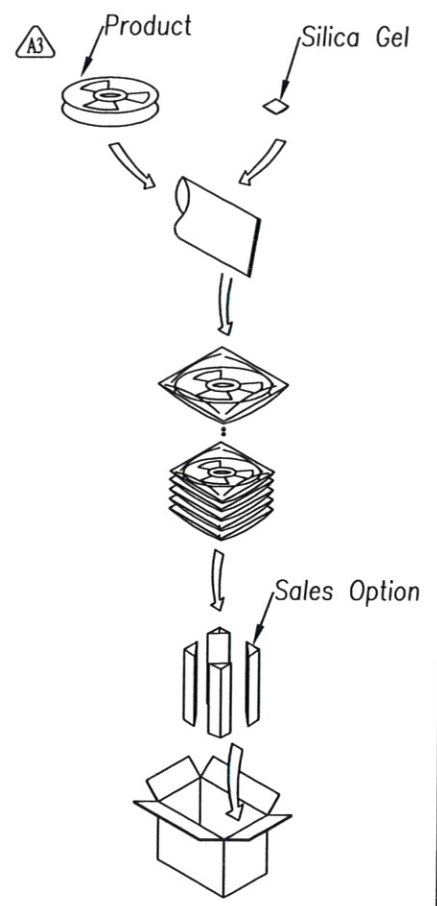
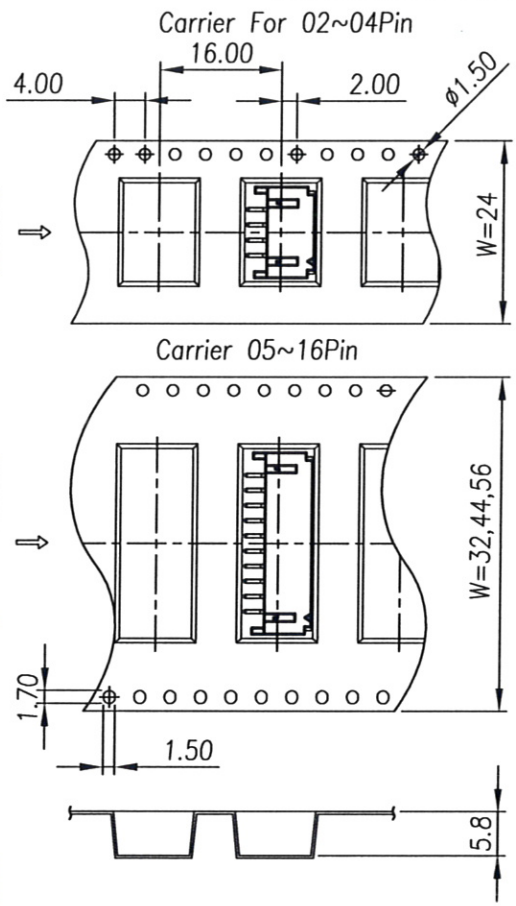
A
B
C
D
E
F


A
B
C
D
E
F



| PIN NO. | W±0.30 | PCS / REEL |
|---------|--------|------------|
| 02 ~ 04 | 24 | 1000 |
| 05 ~ 07 | 32 | |
| 08 ~ 14 | 44 | |
| 15 ~ 16 | 56 | |

Notes:
 1. Material : PS
 2. Part No.: AS05701XXXX12





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| .xxx± 0.15 | .xx'± 0.5' | DRA. Michelle 20150630 | UNITS: mm | SCALE Free |
| | | SIZE: A4 | SHEET 2 / 2 | REV A3 |
| | | V | | |

1 2 3 4 5 6 7 8